

SMD ■ Middle Power LED G67-12S/G2C-D1525L4L82934Z6/2T



Features

- PLCC-2 package
- Top view Green LED
- Wide viewing angle
- Pb-free
- RoHS compliant

Description

The Everlight G67-12S package has high efficacy, Middle power consumption, wide viewing angle and a compact form factor. These features make this package an ideal LED for all lighting applications.

Applications

- Decorative and Entertainment Lighting
- Agriculture Lighting
- General use

Device Selection Guide

Chip Materials	Emitted Color	Resin Color
InGaN	Green	Water Clear

Absolute Maximum Ratings (T_{Soldering}=25°C)

Parameter	Symbol	Rating	Unit
Forward Current	I _F	60	mA
Peak Forward Current (Duty 1/10 @10ms)	I _{FP}	100	mA
Power Dissipation	P _d	230	mW
Operating Temperature	T _{opr}	-40 ~ +85	°C
Electrostatic Discharge(HBM)	ESD	2000	V
Storage Temperature	T _{stg}	-40 ~ +100	°C
Thermal Resistance (Junction / Soldering point)	R _{th J-S}	50	°C/W
Junction Temperature	T _j	115	°C
Soldering Temperature	T _{sol}	Reflow Soldering : 260 °C for 10 sec. Hand Soldering : 350 °C for 3 sec.	

Note:

The products are sensitive to static electricity and must be carefully taken when handling products

Electro-Optical Characteristics (T_{Soldering}=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous flux	I _v	13.0	-----	18.0	lm	I _F =60mA
Forward Voltage	V _F	2.9	-----	3.4	V	I _F =60mA
Viewing Angle	2θ _{1/2}	-----	120	-----	deg	I _F =60mA

Notes:

1. Tolerance of Luminous flux : ±11%.
2. Tolerance of Forward Voltage: ±0.1V.

Bin Range of Luminous flux

Bin Code	Min.	Max.	Unit	Condition
L4	13.0	14.0	lm	I _F =60mA
L5	14.0	15.0		
L6	15.0	16.0		
L7	16.0	17.0		
L8	17.0	18.0		

Notes:
Tolerance of Luminous flux: ±11%

Bin Range of Forward Voltage

Bin Code	Min.	Max.	Unit	Condition
36	2.9	3.0	V	I _F =60mA
37	3.0	3.1		
38	3.1	3.2		
39	3.2	3.3		
40	3.3	3.4		

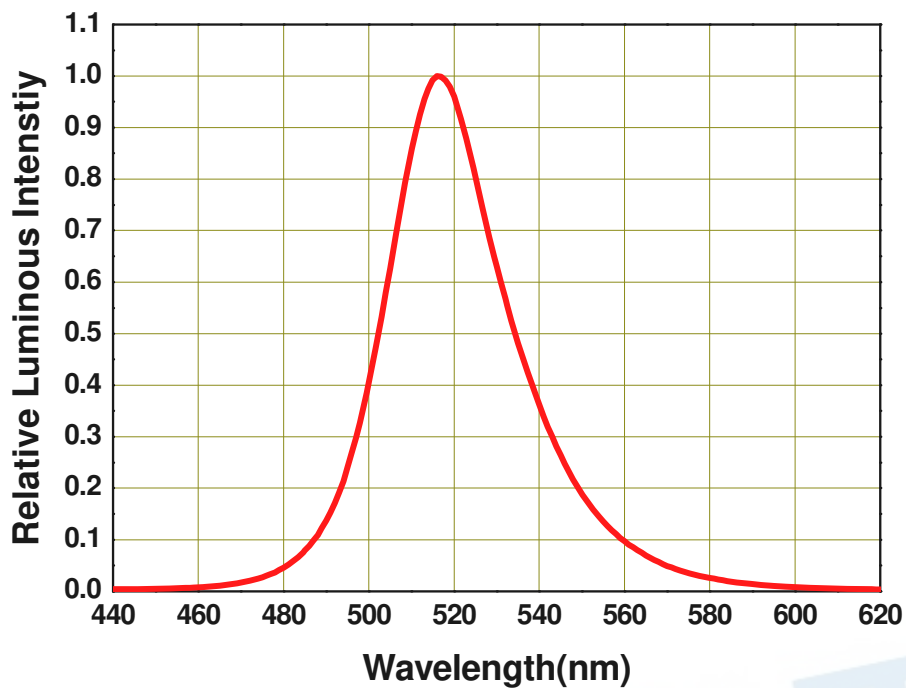
Note:
Tolerance of Forward Voltage: ±0.1V.

Dominant Wavelength Bins

Bin Code	Min.	Max.	Unit	Condition
G51	515	520	nm	I _F =60mA
G52	520	525		

Notes:
Dominant / Peak wavelength measurement tolerance: ±1nm.

Spectrum Distribution



Typical Electro-Optical Characteristics Curves

Fig.1 – Forward Voltage Shift vs. Junction Temperature

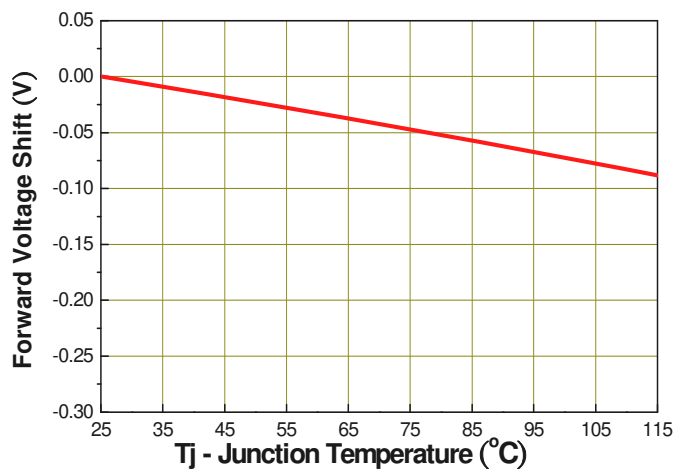
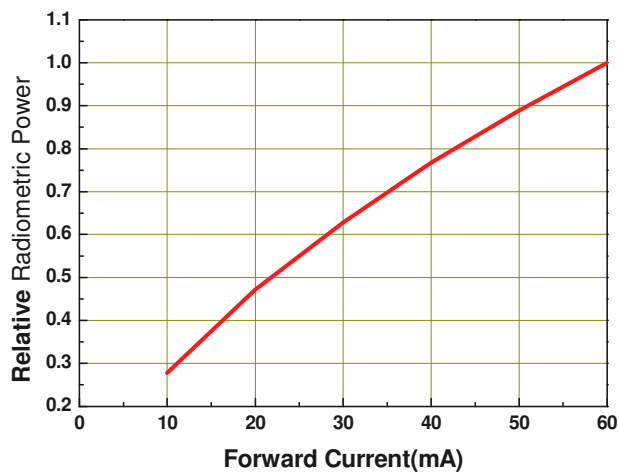


Fig.2 - Relative Radiometric Power vs. Forward Current



Typical Electro-Optical Characteristics Curves

Fig.3 - Relative Luminous Intensity vs. Junction Temperature

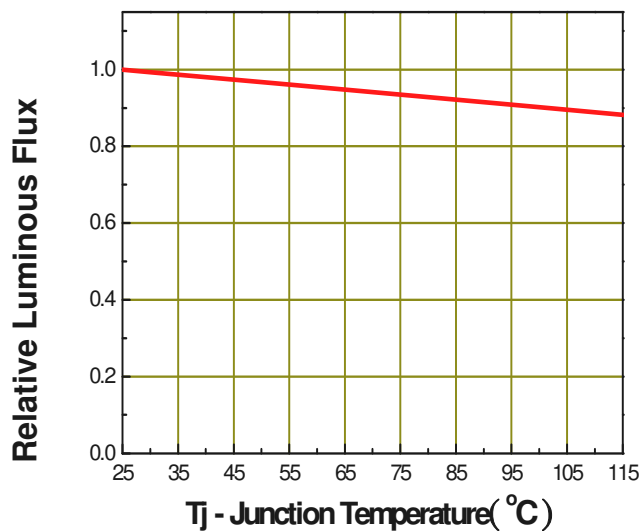


Fig.4 - Forward Current vs. Forward Voltage

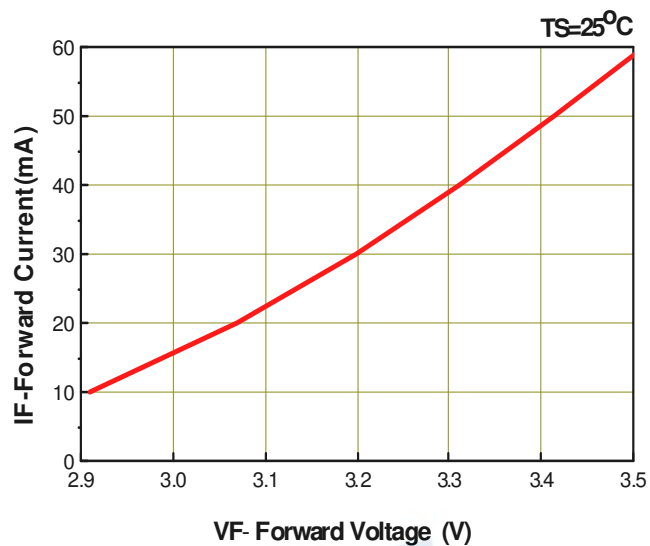


Fig.5 – Max. Driving Forward Current vs. Soldering Temperature

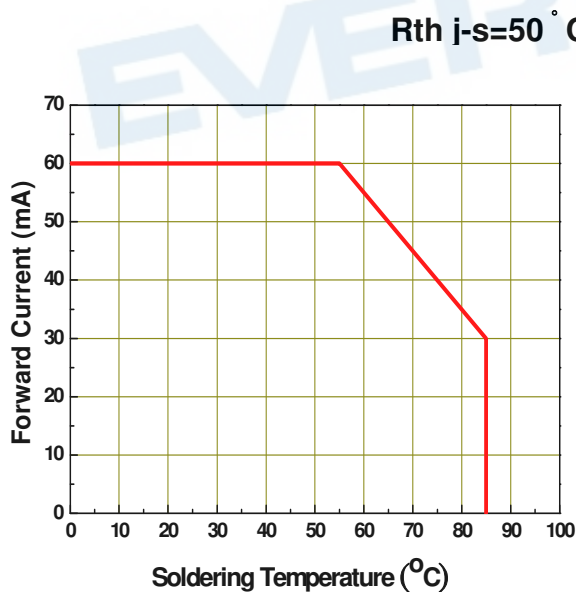
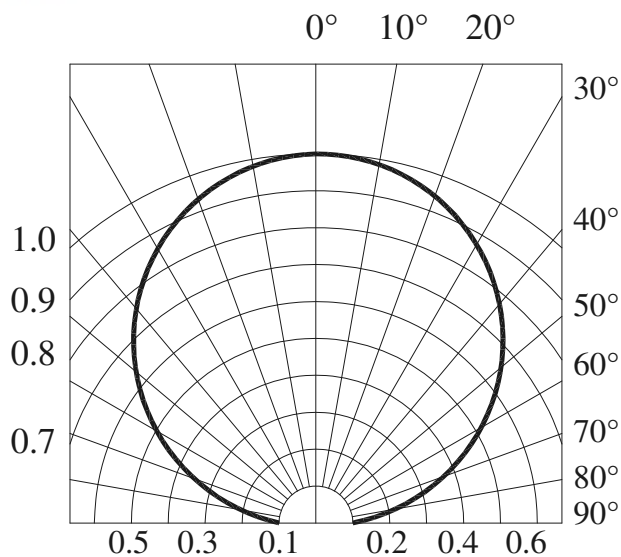
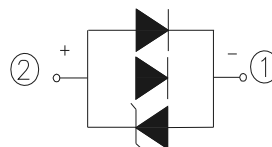
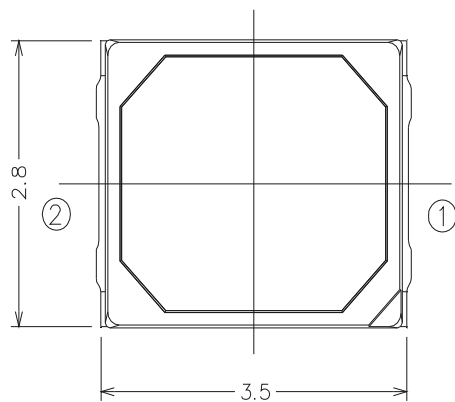


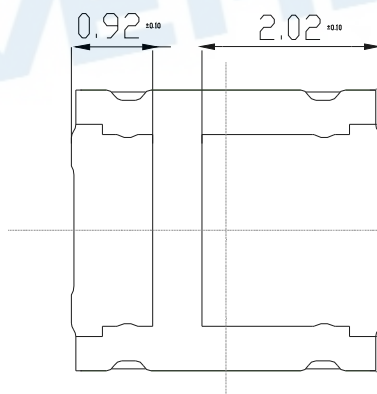
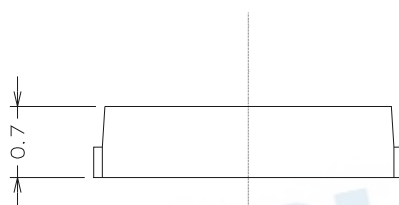
Fig.6 – Radiation Diagram



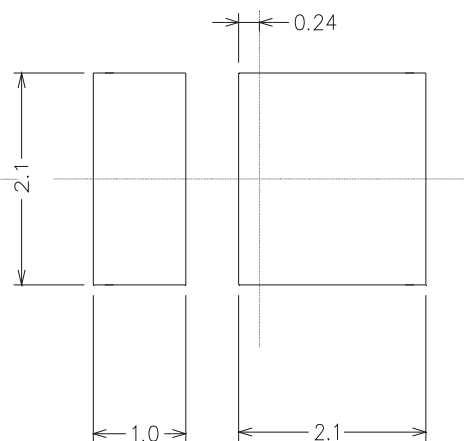
Package Dimension



Polarity



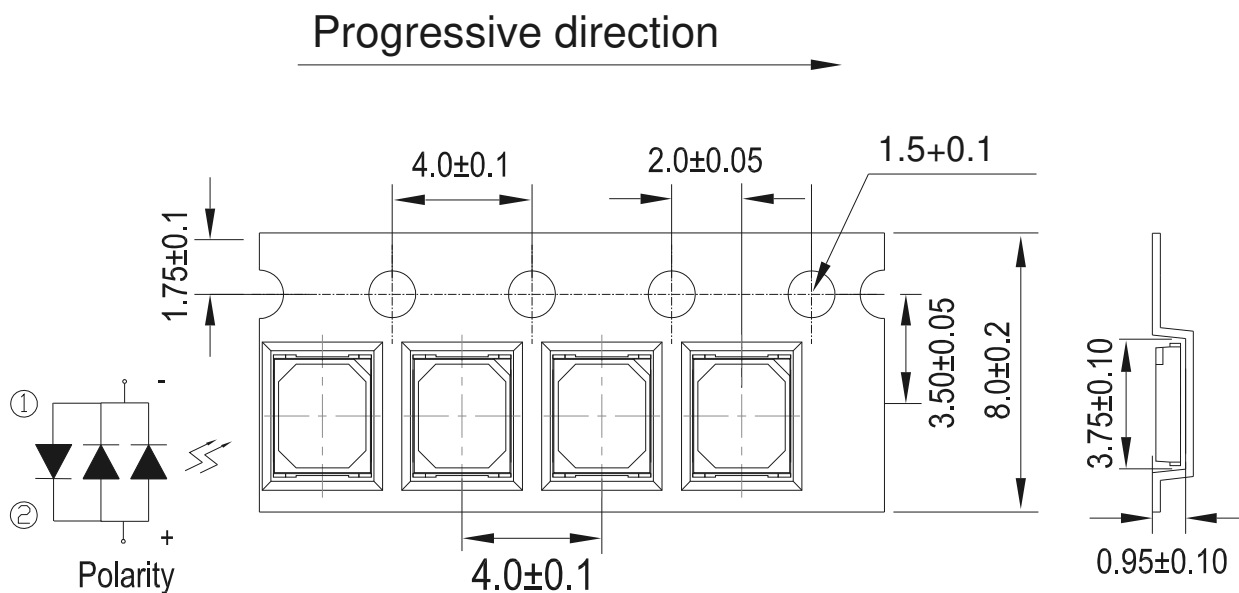
Bot. view



Soldering patterns

Note:
Tolerance unless mentioned is ± 0.15 mm; Unit = mm

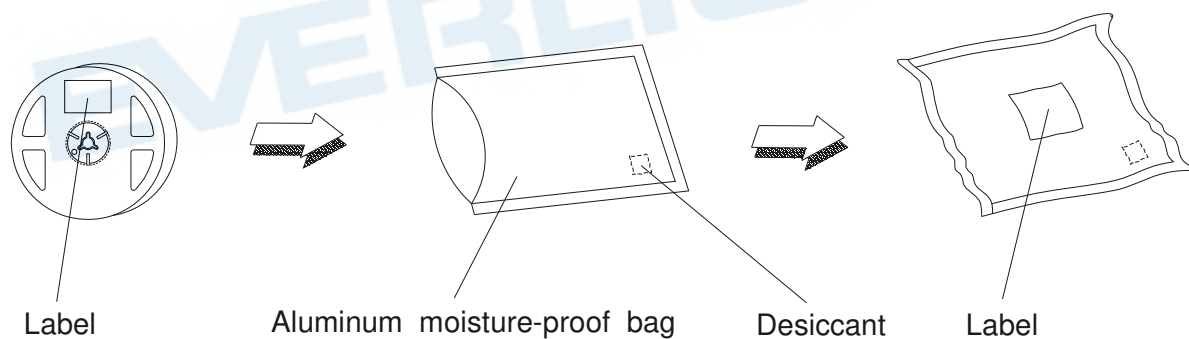
Carrier Tape Dimensions: Loaded Quantity 4000 pcs. Per Reel



Note:

Tolerance unless mentioned is ± 0.1 mm; Unit = mm

Moisture Resistant Packing Process



Reliability Test Items and Conditions

The reliability of products shall be satisfied with items listed below.

Confidence level : 90%

LTPD : 10%

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp. : 260°C/10sec.	6 Min.	22 PCS.	0/1
2	Thermal Shock	H : +100°C 20min ┌ 10 sec L : -10°C 20min	200 Cycles	22 PCS.	0/1
3	Temperature Cycle	H : +100°C 30min ┌ 5 min L : -40°C 30min	200 Cycles	22 PCS.	0/1
4	High Temperature/Humidity Storage	Ta=85°C,85%RH	1000 Hrs.	22 PCS.	0/1
5	High Temperature/Humidity Operation	Ta=85°C,85%RH, I _F = 30mA	1000 Hrs.	22 PCS.	0/1
6	Low Temperature Storage	Ta=-40°C	1000 Hrs.	22 PCS.	0/1
7	High Temperature Storage	Ta=85°C	1000 Hrs.	22 PCS.	0/1
8	Low Temperature Operation Life	Ta=-40°C, I _F = 60 mA	1000 Hrs.	22 PCS.	0/1
9	High Temperature Operation/ Life#1	Ta=25°C, I _F = 60 mA	1000 Hrs.	22 PCS.	0/1
10	High Temperature Operation/ Life#2	Ta=55°C, I _F =60mA	1000 Hrs.	22 PCS.	0/1
11	High Temperature Operation/ Life#3	Ta=85°C, I _F = 30 mA	1000 Hrs.	22 PCS.	0/1

Precautions for Use

1. Over-current-proof

Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

2.2 Before opening the package: The LEDs should be kept at 30°C or less and 90%RH or less.

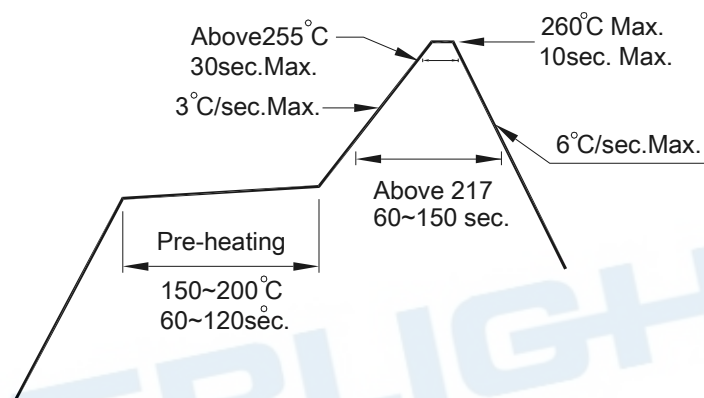
2.3 After opening the package: The LED's floor life is 168 Hrs under 30°C or less and 60% RH or less. If unused LEDs remain, it should be stored in moisture proof packages.

2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment: 60±5°C for 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile



3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

3.4 After soldering, do not warp the circuit board.

4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

